



TG4040 Thermal Putty

REACH Compliant

Features

- · Silicone-type spacer with great long term reliability
- · Lower thermal contact impedance than thermal pads
- · Physical property in between liquid and solid state
- · Gap fillers for uneven or irregular surfaces of heat sources and heat sink
- · Applicable for dispenser

Application:

Electronic Components - 5G, Aerospace, AI, AIoT, AR/VR/MR/XR, Automotive, Consumer Devices, Datacom, Electric Vehicle, Electronic Products, Energy Storage, Industrial, Lighting Equipment, Medical, Military, Netcom, Panel, Power Electronics, Robot, Servers, Smart Home, Telecom, etc.

Operation Manual









③ Close the cover.



4 Take off the plug.

(The putty in the picture does not represent the actual product.)

Properties

Thermal Conductivity: 3.2 W/m•K

0.8 1.2 1.4 1.6 1.7 1.8 2.2 3.2 3.6 4.0 4.5 5.0 20

Properties	Unit	TG4040	Tolerance	Test Method
Thermal Conductivity	W/m•K	3.2	±0.3	ASTM D5470 Modified
Color	-	Blue	-	-
Viscosity @0.5rpm	Pa∙s	250(±100)	-	Brookfield
Density	g/cm³	2.9	±5%	ASTM D792
Volume Resistivity	Ohm-mm	10 ¹³	-	ASTM D257
Operating Temperature	° C	-50~+180	-	-
Standard Package	-	Tube/Pot	-	-

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